Layer Stacking

TOP

BOTTOM

Overall Board Thickness: 62 Mil
Soldermask Color: RED
Silkscreen Color: White
Drill hole tolerance: +/- 3 Mil

<table>
<thead>
<tr>
<th>SIZE</th>
<th>QTY</th>
<th>SYM</th>
<th>PLATED</th>
<th>TOL</th>
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<td>122</td>
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<td>X</td>
<td>NO</td>
<td>+/-0.0</td>
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<tr>
<td>13</td>
<td>93</td>
<td>□</td>
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<tr>
<td>47.24</td>
<td>4</td>
<td>◊</td>
<td>NO</td>
<td>+/-0.0</td>
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<td>35.04</td>
<td>32</td>
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<td>†A</td>
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